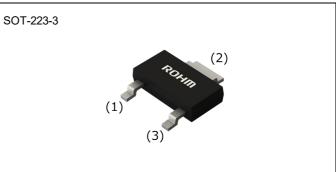


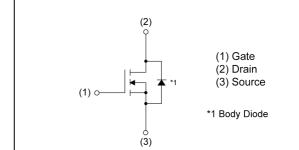
R6003KND4 Nch 600V 1.3A Power MOSFET

V _{DSS}	600V
R _{DS(on)} (Max.)	1.5Ω
I _D	±1.3A
P _D	7.8W

Outline



Inner circuit



Application

Features

1) Low on-resistance

2) Fast switching speed3) Parallel use is easy

4) Pb-free plating ; RoHS compliant

Switching applications

Packaging specifications

Packing	Embossed Tape
Packing code	TL1
Marking	R6003KND4
Quantity (pcs)	4000

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	600	V
Continuous drain current (T _c = 25	5°C)	۱ _D *1	±1.3	А
Pulsed drain current	I _{DP} *2	±6.0	А	
Octor Octores welltage	static		±20	V
Gate - Source voltage	AC(f>1Hz)	V_{GSS}	±30	V
Avalanche current, single pulse		I _{AS}	0.5	А
Avalanche energy, single pulse		E_{AS}^{*3}	13.4	mJ
Power dissipation ($T_c = 25^{\circ}C$)		P _D	7.8	W
Junction temperature		Τ _j	150	°C
Operating junction and storage temperature range		T _{stg}	-55 to +150	°C

•Thermal resistance

Deremeter	Cumph of	Values			Lincit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - solder point	R_{thJS}^{*4}	-	-	16.1	°C/W
Thermal resistance, junction - ambient	R_{thJA}^{*5}	-	-	160	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Ofile
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	600	-	-	V
		V _{DS} = 600V, V _{GS} = 0V				
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μA
		$T_j = 125^{\circ}C$	-	-	1000	
Gate - Source leakage current	I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = 10V, I _D = 1mA	3.5	-	5.5	V
		V _{GS} = 10V, I _D = 1A				
Static drain - source on - state resistance	R _{DS(on)} *6	$T_j = 25^{\circ}C$	-	1.3	1.5	Ω
		$T_j = 125^{\circ}C$	-	2.5	-	
Gate resistance	R _G	f = 1MHz, open drain	-	3.2	-	Ω



• Electrical characteristics ($T_a = 25^{\circ}C$)

Devenuetor	Cyrrada al	Conditions	Values			L lucit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Transfer Admittance	Y _{fs} ⁵	V _{DS} = 10V, I _D = 1.5A	0.8	1.6	-	S	
Input capacitance	C _{iss}	V _{GS} = 0V	-	185	-		
Output capacitance	C _{oss}	V _{DS} = 25V	-	205	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	12	-		
Turn - on delay time	t _{d(on)} *6	$V_{DD} \simeq 300$ V, V_{GS} = 10V	-	17	-		
Rise time	t _r *6	I _D = 1.5A	-	17	-	20	
Turn - off delay time	t _{d(off)} *6	$R_L \simeq 200\Omega$	-	32	-	ns	
Fall time	t _f *6	R _G = 10Ω	-	40	-		

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Currence of	Conditions	Values			L lucit
Parameter	Symbol	mbol Conditions –		Тур.	Max.	Unit
Total gate charge	Q_{g}^{*6}	V _{DD} ≃ 300V	-	8	-	
Gate - Source charge	Q _{gs} *6	I _D = 3A	-	2.3	-	nC
Gate - Drain charge	Q _{gd} *6	V _{GS} = 10V	-	3.5	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300$ V, I _D = 3A	-	6.8	-	V

*1 Limited only by maximum junction temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L \doteqdot 100mH, V_{DD}=50V, R_G=25 Ω , starting T_i=25°C

*4 T_s=25°C

*5 Mounted on an epoxy PCB FR4(20mm × 20mm × 0.8 mm)

*6 Pulsed



•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Source current	۱ _S *1	- T _C = 25°C	-	-	1.3	А
Pulsed source current	I_{SP}^{*2}		-	-	6.0	А
Source-Drain voltage	V_{SD}^{*6}	V _{GS} = 0V, I _S = 3.0A	-	-	1.5	V
Reverse recovery time	t _{rr} *6		-	240	-	ns
Reverse recovery charge	Q _{rr} *6	I _S = 3.0A di/dt = 100A/µs	-	0.86	-	μC
Peak reverse recovery current	۲ <mark>,</mark> *6		-	7.0	-	А



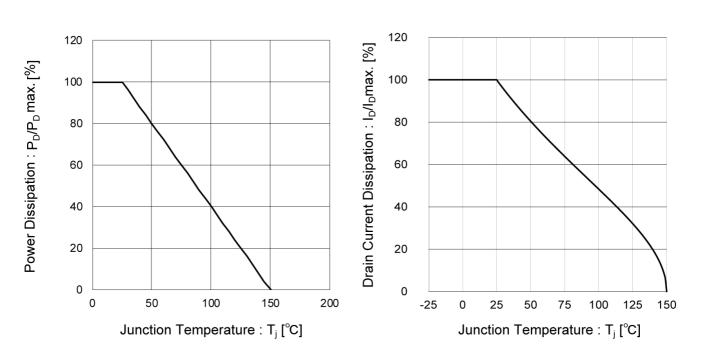


Fig.1 Power Dissipation Derating Curve

Fig.3 Transient Thermal Resistance

vs. Pulse Width



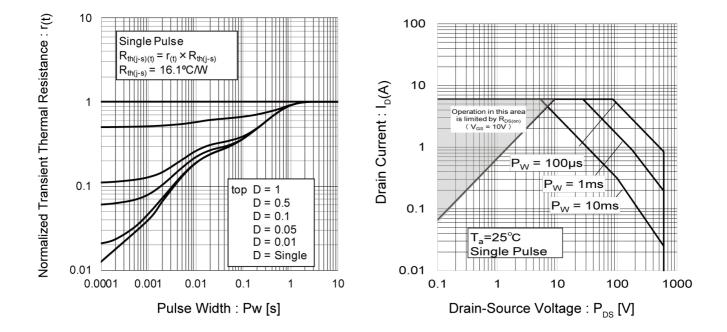




Fig.2 Drain Current Derating Curve

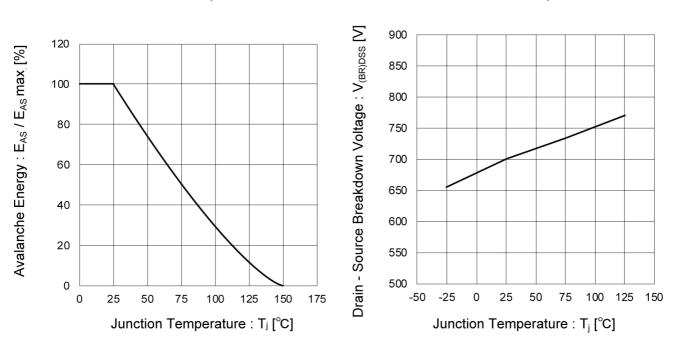


Fig.5 Avalanche Energy DeratingCurve vs. Junction Temperature

Fig.8 Typical Output Characteristics(II)

Fig.6 Breakdown Voltage

vs. Junction Temperature

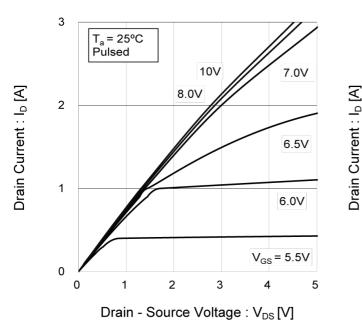
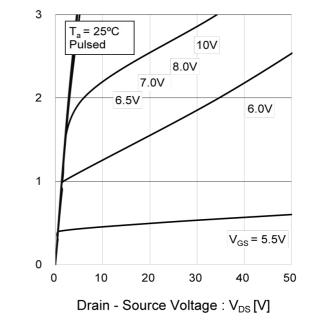


Fig.7 Typical Output Characteristics(I)





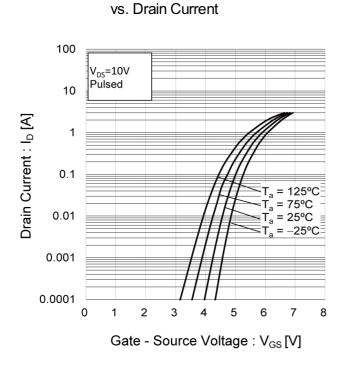


Fig.9 Gate Threshold Voltage

Fig.10 Gate Threshold Voltage vs. Junction Temperature

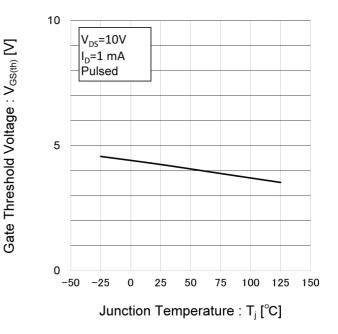
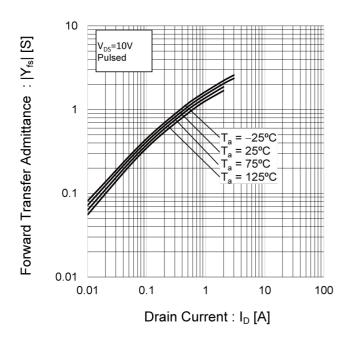


Fig.11 Forward Transfer Admittance vs. Drain Current





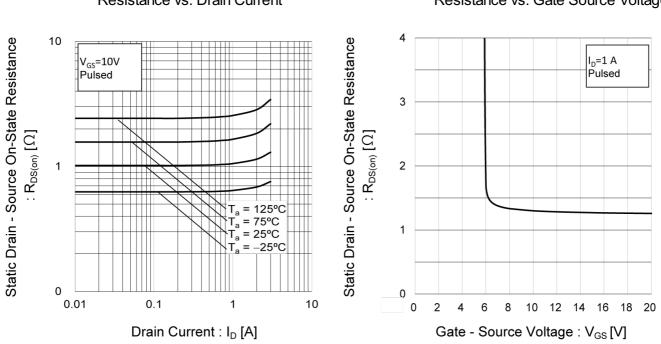


Fig.12 Static Drain - Source On - State Resistance vs. Drain Current Fig.13 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

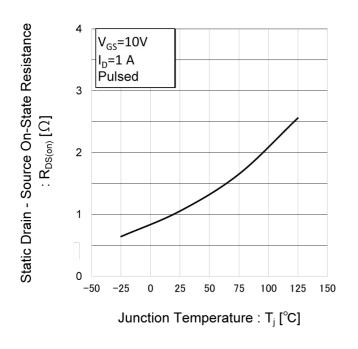




Fig.15 Typical Capacitance

vs. Drain - Source Voltage

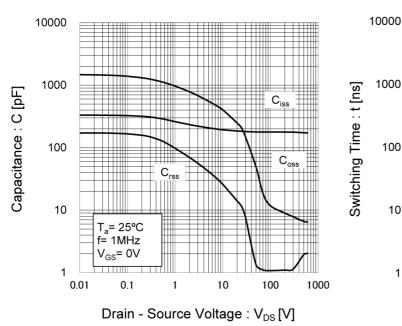
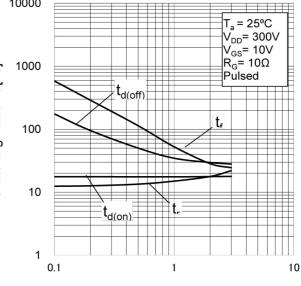
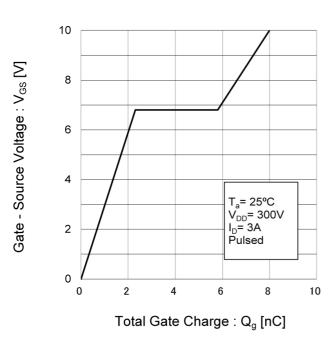


Fig.16 Switching Characteristics



Drain Current : I_D [A]

Fig.17 Typical Gate Charge





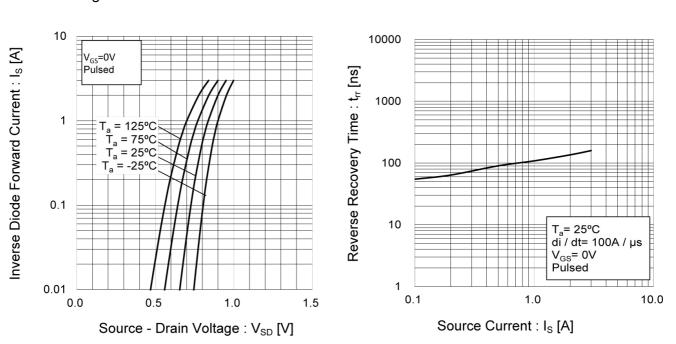


Fig.18 Souce Current vs. Source-Drain Voltage

Fig.19 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

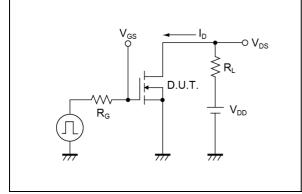


Fig.2-1 Gate Charge Measurement Circuit

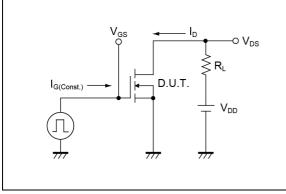


Fig.3-1 Avalanche Measurement Circuit

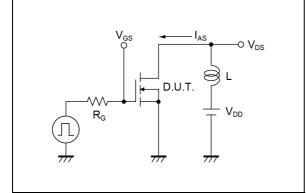


Fig.4-1 Reverse Recovery Time Measurement Circuit

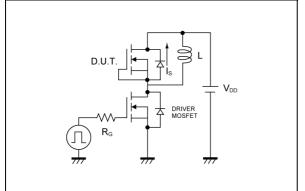


Fig.1-2 Switching Waveforms

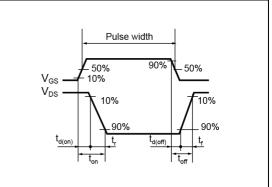


Fig.2-2 Gate Charge Waveform

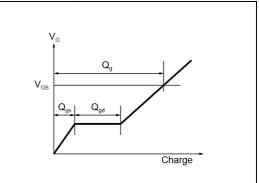


Fig.3-2 Avalanche Waveform

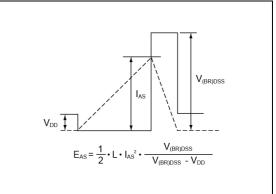
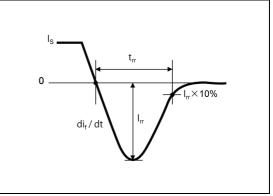
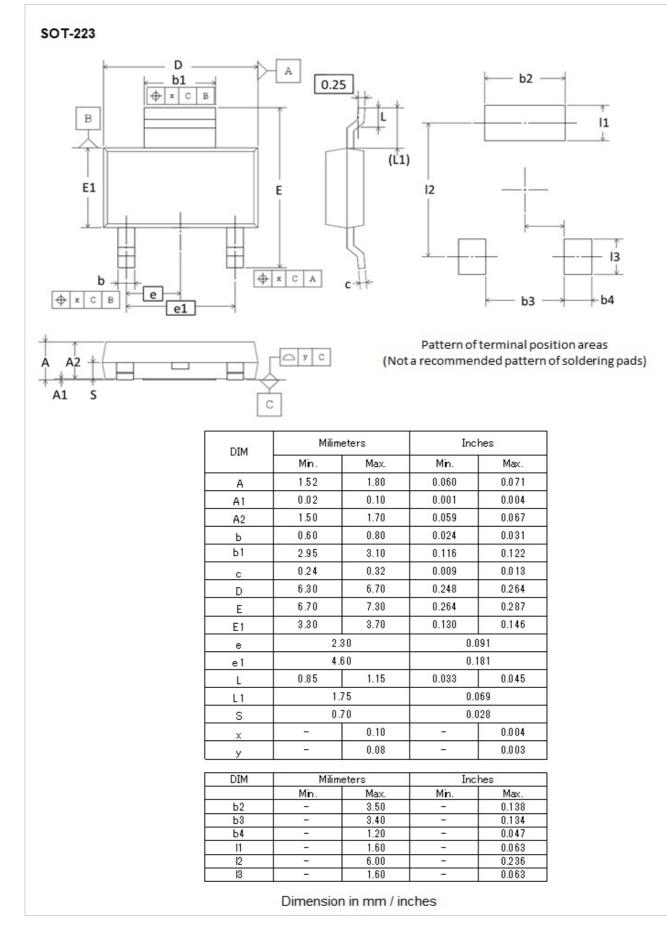


Fig.4-2Reverse Recovery Time Waveform





Dimensions





ROHM

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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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